

SOP-8 Mechanical Package Outline Drawing (POD)

Standard 8-Pin Small Outline Package Dimensions & PCB Footprint

1. Package Dimensions

Body Length (E)	4.90 mm (typ) / 5.00 mm (max)
Body Width (D)	3.90 mm (typ) / 4.00 mm (max)
Total Width (E1)	5.80 mm (min) / 6.20 mm (max)
Lead Pitch (e)	1.27 mm (nominal)
Lead Width (b)	0.33 mm (min) / 0.51 mm (max)
Total Height (A)	1.35 mm (min) / 1.75 mm (max)

2. Recommended PCB Land Pattern

Pad Length: 1.50 mm | Pad Width: 0.60 mm | Pitch: 1.27 mm | Overall Span: 6.80 mm. Standard Jedec MS-012 AA compliance.

3. Thermal Resistance

Theta-JA: 150 °C/W (standard JEDEC 2-layer PCB) | Theta-JC: 45 °C/W.